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(54) **METHOD FOR MANUFACTURING  
ELECTRONICS ASSEMBLY AND  
ELECTRONICS ASSEMBLY**

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**ABSTRACT**

A method for manufacturing an electronics assembly, includes obtaining or producing an electronics module, which includes a first circuitry on a first surface at a first side of a circuit board, at least one electronics component on the circuit board in electrical connection with the first circuitry, and at least one first connection portion on the first surface and/or an adjacent side surface at a peripheral portion of the circuit board, wherein the at least one first connection portion is electrically connected to or comprised in the first circuitry. The method further includes arranging the electronics module on a second substrate including a second connection portion connected to a second circuitry on a surface of the second substrate and arranging electrically conductive joint material onto the first and second connection portions to extend between them for electrically connecting the electronics module to the second circuitry.

